

Title: HIGH-DENSITY MULTICHIP MODULE PACKAGE
Inventor's Name: HO et al
Application No.: New Application
Docket No.: 025796-00014

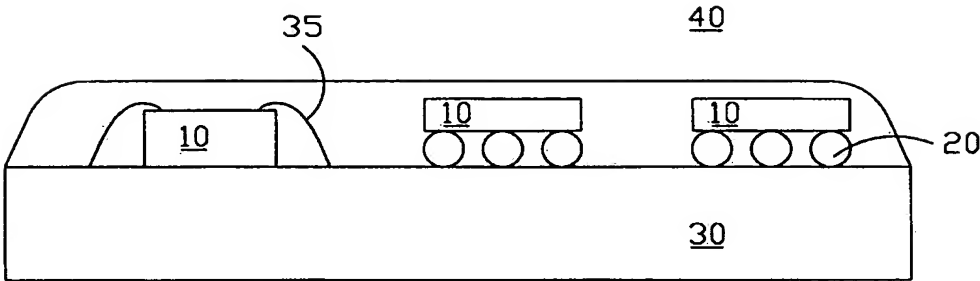


FIG.1(Prior Art)

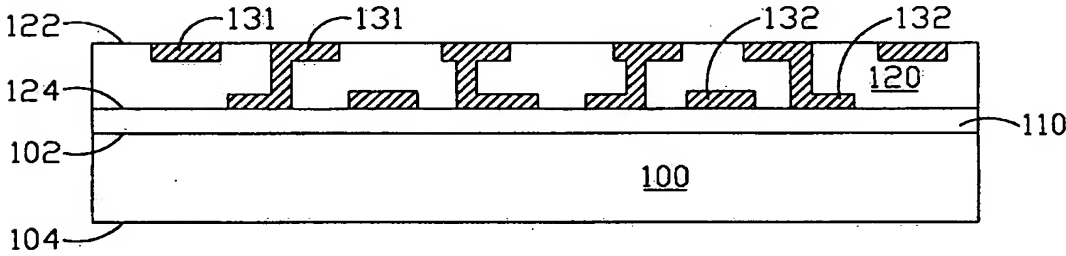


FIG. 2

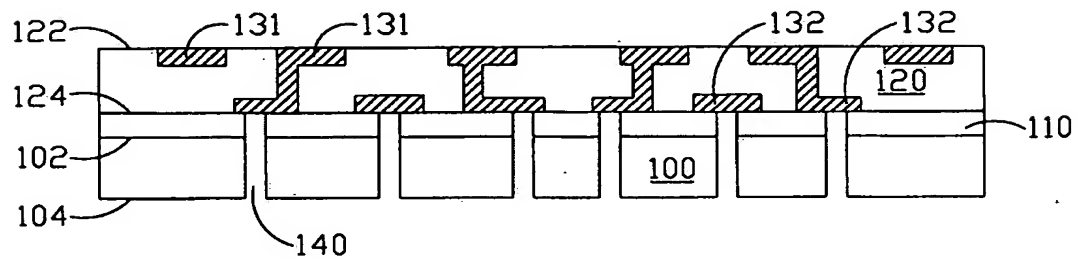


FIG.3

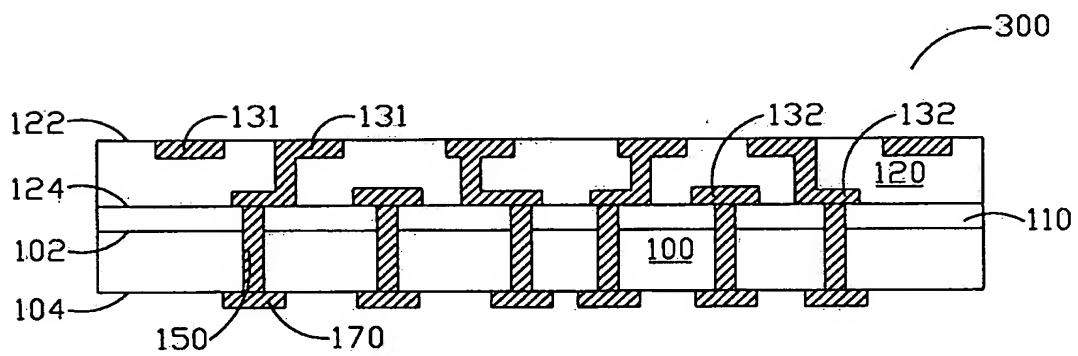


FIG.4

Docket No.: 025796-00014

5

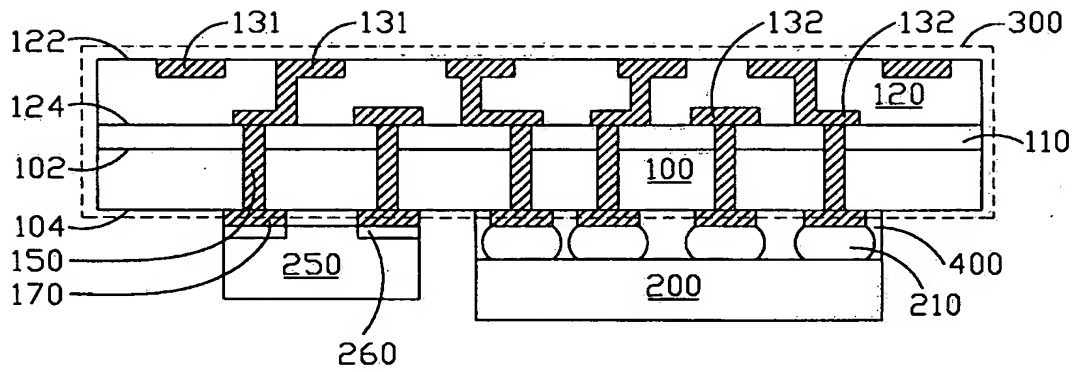


FIG.5

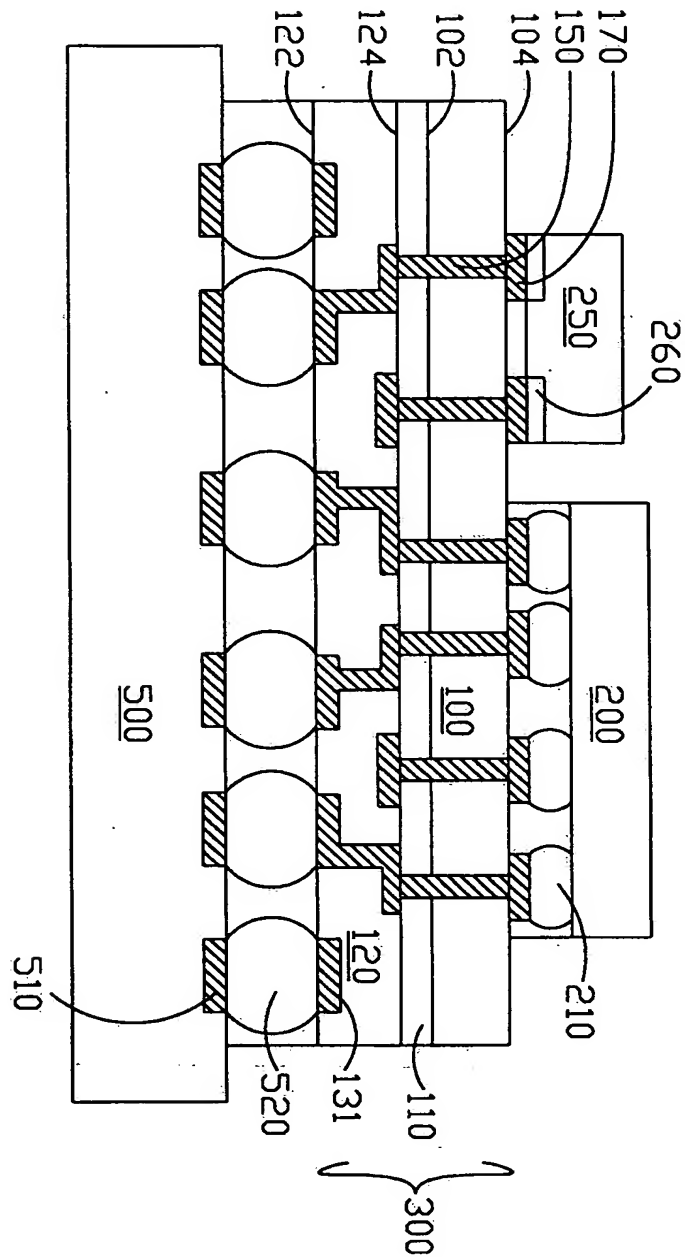


FIG. 6

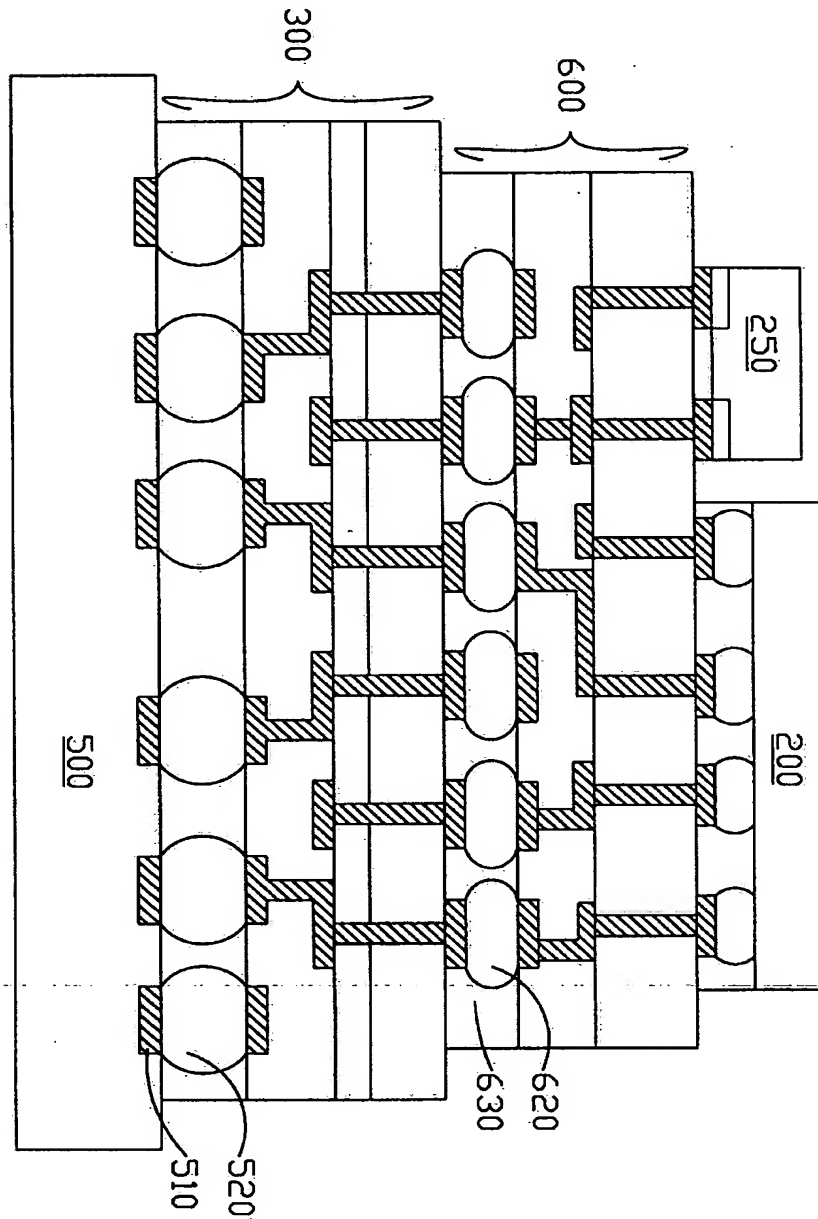


FIG. 7